



BSI Standards Publication

Integrated circuits — Measurement of electromagnetic emissions

Part 3: Measurement of radiated
emissions — Surface scan method

National foreword

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**Integrated circuits – Measurement of electromagnetic emissions –
Part 3: Measurement of radiated emissions – Surface scan method**

**Circuits intégrés – Mesure des émissions électromagnétiques –
Partie 3: Mesure des émissions rayonnées – Méthode de balayage en surface**

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CONTENTS

FOREWORD.....	5
INTRODUCTION.....	7
1 Scope.....	8
2 Normative references	8
3 Terms, definitions and abbreviations	8
3.1 Terms and definitions	8
3.2 Abbreviations	9
4 General	9
5 Test conditions	10
5.1 General.....	10
5.2 Supply voltage	10
5.3 Frequency range	10
6 Test equipment.....	10
6.1 General.....	10
6.2 Shielding.....	10
6.3 RF measuring instrument	10
6.4 Preamplifier	10
6.5 Cables	11
6.6 Near-field probe	11
6.6.1 General	11
6.6.2 Magnetic (H) field probe	11
6.6.3 Electric (E) field probe.....	11
6.6.4 Combined electric and magnetic (E/H) field probe.....	11
6.6.5 Probe-positioning and data acquisition system.....	11
7 Test setup	12
7.1 General.....	12
7.2 Test configuration	12
7.3 Test circuit board	14
7.4 Probe-positioning system software setup	14
7.5 DUT software	14
8 Test procedure	14
8.1 General.....	14
8.2 Ambient conditions	14
8.3 Operational check	14
8.4 Test technique	15
9 Test report	16
9.1 General.....	16
9.2 Measurement conditions.....	16
9.3 Probe design and calibration	16
9.4 Measurement data	16
9.5 Post-processing	17
9.6 Data exchange.....	17
Annex A (normative) Calibration of near-field probes	18
A.1 General.....	18
A.2 Test equipment	20
A.2.1 General	20

A.2.2	PCB with microstrip line	20
A.3	Calibration setup	21
A.4	Calibration procedure	22
Annex B (informative)	Discrete electric and magnetic field probes	25
B.1	General	25
B.2	Probe electrical description	25
B.3	Probe physical description	26
B.3.1	General	26
B.3.2	Electric field probe	26
B.3.3	Magnetic field probe	26
Annex C (informative)	Combined electric and magnetic field probe example	28
C.1	General	28
C.2	Probe electrical description	28
C.3	Probe physical description	29
C.4	Measurement and data acquisition system	29
Annex D (informative)	Coordinate systems	31
D.1	General	31
D.2	Cartesian coordinate system	31
D.3	Cylindrical coordinate system	32
D.4	Spherical coordinate system	33
D.5	Coordinate system conversion	33
Bibliography	34
Figure 1	– Example of probe-positioning system	12
Figure 2	– One-input RF measurement setup	13
Figure 3	– Two-input RF measurement setup with reference probe	13
Figure 4	– Two-input RF measurement setup with reference signal	13
Figure 5	– Examples of data overlay on an image of the DUT (Contour chart)	16
Figure A.1	– Typical probe factor against frequency	20
Figure A.2	– Microstrip line for calibration (transverse cross-section)	21
Figure A.3	– Microstrip line for calibration (longitudinal cross-section)	21
Figure A.4	– Probe calibration setup	22
Figure A.5	– Scan direction across Microstrip line	22
Figure A.6	– Typical plot of measured signal level and simulated field strength (H_x)	24
Figure A.7	– Typical plot of measured signal level and simulated field strength (H_z)	24
Figure B.1	– Electric and magnetic field probe schematics	25
Figure B.2	– Example of electric field probe construction (E_z)	26
Figure B.3	– Example of magnetic field probe construction (H_x or H_y)	27
Figure C.1	– Electromagnetic field probe schematic	28
Figure C.2	– Electromagnetic field probe construction	29
Figure C.3	– Measurement and data acquisition system overview	30
Figure C.4	– Measurement and data acquisition system detail	30
Figure D.1	– Right-hand Cartesian coordinate system (preferred)	31
Figure D.2	– Left-hand Cartesian coordinate system	32
Figure D.3	– Cylindrical coordinate system	32
Figure D.4	– Spherical coordinate system	33

Table A.1 – Probe factor linear units	19
Table A.2 – Probe factor logarithmic units	19
Table A.3 – Dimensions for 50 Ω microstrip.....	21
Table D.1 – Coordinate system conversion.....	33

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

INTEGRATED CIRCUITS – MEASUREMENT OF ELECTROMAGNETIC EMISSIONS –

Part 3: Measurement of radiated emissions – Surface scan method

FOREWORD

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- the required support cannot be obtained for the publication of an International Standard, despite repeated efforts, or
- the subject is still under technical development or where, for any other reason, there is the future but no immediate possibility of an agreement on an International Standard.

Technical specifications are subject to review within three years of publication to decide whether they can be transformed into International Standards.

IEC 61967-3, which is a technical specification, has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2005. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) Removal of:
 - 9.4 Data analysis;
 - Annex D – Analysing the data from near-field surface scanning.
- b) Addition of:
 - Introduction
 - 9.4 Measurement data
 - 9.5 Post-processing
 - 9.6 Data exchange
 - Annex D – Coordinate systems
- c) Expansion of:
 - 8.4 Test technique
 - Annex A – Calibration of near-field probes

The text of this technical specification is based on the following documents:

Enquiry draft	Report on voting
47A/925/DTS	47A/927/RVC

Full information on the voting for the approval of this technical specification can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61967 series, published under the general title *Integrated circuits – Measurement of electromagnetic emissions*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- transformed into an International standard,
- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

Techniques for scanning near-fields radiated by integrated circuits and their surrounding environment can identify the areas of radiation, which may cause interference to nearby devices. The ability to associate magnetic or electric field strengths with a particular location on a device can provide valuable information for improvement of an IC both in terms of functionality and EMC performance.

Near-field scan techniques have considerably evolved over recent years. The improved sensitivity, bandwidth and spatial resolution of the probes offer analysis of integrated circuits operating into the gigahertz range. The ability to measure radiation both in the frequency and time domain allows not only analysis of fields generated by an IC, but also fields generated by externally applied disturbances propagating through the device. Post-processing can considerably enhance the resolution of a near-field scan measurement and the measured data can be shown in various ways, per user's choice.

INTEGRATED CIRCUITS – MEASUREMENT OF ELECTROMAGNETIC EMISSIONS –

Part 3: Measurement of radiated emissions – Surface scan method

1 Scope

This part of IEC 61967 provides a test procedure which defines an evaluation method for the near electric, magnetic or electromagnetic field components at or near the surface of an integrated circuit (IC). This diagnostic procedure is intended for IC architectural analysis such as floor planning and power distribution optimization. This test procedure is applicable to measurements on an IC mounted on any circuit board that is accessible to the scanning probe. In some cases it is useful to scan not only the IC but also its environment. For comparison of surface scan emissions between different ICs, the standardized test board defined in IEC 61967-1 should be used.

This measurement method provides a mapping of the electric or magnetic near-field emissions over the IC. The resolution of the measurement is determined by the capability of the measurement probe and the precision of the probe-positioning system. This method is intended for use up to 6 GHz. Extending the upper limit of frequency is possible with existing probe technology but is beyond the scope of this specification. Measurements may be carried out in the frequency domain or in the time domain.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050(all parts), *International Electrotechnical Vocabulary* (available at <<http://www.electropedia.org>>)

IEC 61967-1, *Integrated Circuits – Measurement of electromagnetic emissions, 150 kHz to 1 GHz – Part 1: General conditions and definitions*

3 Terms, definitions and abbreviations

3.1 Terms and definitions

For the purpose of this document, the terms and definitions given in IEC 61967-1, IEC 60050-131 and IEC 60050-161, as well as the following apply.

3.1.1

altitude

distance between the tip of the near-field probe and the reference plane of the scan (e.g. the PCB, the upper surface of the package)

Note 1 to entry: The term “altitude” refers to the vertical direction in a Cartesian coordinate system (Z-axis) in this document.